

ABSTRACT OF THE DISCLOSURE

A heat conductivity and brightness enhancing structure for light-emitting diode, including a bracket having a cathode leg support. A bowl structure is formed on upper end of the cathode leg support for resting a light-emitting chip therein. At least one depression is formed on a bottommost section of the bowl for receiving an adhesive therein. The depression has a diameter or area smaller than the bottom face of the chip. The adhesive is filled into the depression for adhering one or more chip. The other portions of the bottom face of the bowl, which contact with the chip is free from the adhesive and can achieve good heat conduction and radiation effect. At least one column hole is formed in the cathode leg support from a hollow section of the bottom of the bracket to the depression of the bowl. During manufacturing procedure, the adhesive can be heated, molten and exhausted from the column hole. The column hole serves as a passage for air convection, whereby the heat generated by the chip can be dissipated.